

CLAIM AMENDMENTS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1 - 10 (canceled).

Claim 11 (currently amended). An optical module, comprising:

a circuit carrier;

a semiconductor element and a housing encasing said semiconductor element disposed on said circuit carrier; and

a lens unit disposed for projecting electromagnetic radiation onto said semiconductor element, said lens unit including at least one lens and a lens support supporting said lens, said lens support forming an integral component of said housing of said semiconductor element;

wherein said lens support is formed of a thermoplastic material and said housing is formed of a thermosetting material.

Claim 12 (previously presented). The optical module according to claim 11, wherein said at least one lens is one of a plurality of mutually aligned lenses supported in said lens support.

Claim 13 (previously presented). The optical module according to claim 11, wherein said lens support supporting said at least one lens is integrally formed in one piece with said housing.

Claim 14 (canceled).

Claim 15 (previously presented). The optical module according to claim 11, wherein said lens support supporting said at least one lens is formed on said housing of said semiconductor element.

Claim 16 (previously presented). The optical module according to claim 15, wherein said lens support is formed onto said housing in a two-component injection process.

Claim 17 (canceled).

Claim 18 (previously presented). The optical module according to claim 11, wherein said lens unit includes a plurality of lenses in form of a package, wherein the lenses and at least one diaphragm are in direct contact with one another, and relative positions of said lenses and said diaphragm relative to one another are defined by a geometry of said lenses and/or of said diaphragm.

Claim 19 (previously presented). The optical module according to claim 11, wherein said lens unit includes a plurality of lenses in form of a package, wherein the lenses are in direct contact with one another, and positions of said lenses relative to one another are defined by a geometry of said lenses.

Claim 20 (previously presented). The optical module according to claim 12, wherein only one lens of said plurality of lenses is in direct contact with said lens holder.

Claim 21 (previously presented). The optical module according to claim 20, wherein said one lens is sealed watertight and dustproof with said lens holder.

Claim 22 (previously presented). The optical module according to claim 20, wherein said one lens is attached to said lens holder by at least one connection selected from ultrasound, laser soldering, and adhesives.

Claim 23 (previously presented). The optical module according to claim 12, wherein said lenses are snapped into said lens holder by latching engagement.

Claim 24 (previously presented). The optical module according to claim 23, wherein said lenses, or an optional diaphragm, are formed with a relatively hard component and a relatively soft component for forming a watertight and dustproof seal, and said soft component forms a seal in an area of said lenses.

Claim 25 (previously presented). The optical module according to claim 12, which comprises a retaining element attaching said lenses in said lens support.

Claim 26 (previously presented). The optical module according to claim 25, wherein said retaining element has a relatively hard component and a permanently elastic component formed on an area adjoining said at least one lens for forming a seal and compensating for stress, and wherein said hard component of said retaining element is joined to said lens holder.

Claim 27 (previously presented). The optical module according to claim 26, wherein said hard component is attached to said lens support by one or more attachment methods selected from the group consisting of ultrasound, laser soldering, adhesive or riveting processes, and a snap or screw connection.

Claim 28 (previously presented). The optical module according to claim 11, which comprises pigments applied to said lens support for setting a black and/or dull or totally reflective finish, for preventing unwanted optical effects.

Claim 29 (previously presented). The optical module according to claim 28, wherein said pigments are disposed to prevent unwanted optical effects due to a lateral incidence of light.

Claim 30 (currently amended). An optical system, ~~comprises an~~ comprising the optical module according to claim 11.

Claim 31 (new). An optical module, comprising:

a circuit carrier;

a semiconductor element and a housing encasing said semiconductor element disposed on said circuit carrier; and

a lens unit disposed for projecting electromagnetic radiation onto said semiconductor element, said lens unit including a plurality of mutually aligned lenses and a lens support supporting said plurality of lenses, said lens support forming an integral component of said housing of said semiconductor element;

said plurality of lenses snapped into said lens holder by latching engagement.

Claim 32 (new). The optical module according to claim 31, wherein at least one of said plurality of lenses is formed with a relatively hard component and a relatively soft component for forming a watertight and dustproof seal, and said soft component forms a seal in an area of said plurality of lenses.

Claim 33 (new). The optical module according to claim 31, further comprising a diaphragm formed with a relatively hard component and a relatively soft component for forming a watertight and dustproof seal, said soft component forming a seal in an area of said plurality of lenses.

Claim 34 (new). An optical module, comprising:

a circuit carrier;

a semiconductor element and a housing encasing said semiconductor element disposed on said circuit carrier; and

a lens unit disposed for projecting electromagnetic radiation onto said semiconductor element, said lens unit including a plurality of mutually aligned lenses and a lens support supporting said plurality of lenses, said lens support forming an integral component of said housing of said semiconductor element;

only one lens of said plurality of lenses being in direct contact with said lens holder.

Claim 35 (new). The optical module according to claim 34, wherein said one lens is sealed watertight and dustproof with said lens holder.